TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type

SSM3J35CT

- High-Speed Switching Applications
- Analog Switch Applications
- 1.2-V drive

• Low ON-resistance : R_{ON} = 44 Ω (max) (@V_{GS} = -1.2 V)

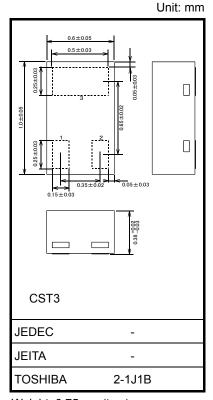
: R_{on} = 22 Ω (max) (@V_{GS} = -1.5 V) : R_{on} = 11 Ω (max) (@V_{GS} = -2.5 V)

: R_{on} = 8 Ω (max) (@V_{GS} = -4.0 V)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	-20	V	
Gate-source voltage		V_{GSS}	±10	V	
Drain current	DC	I _D	-100	mA	
	Pulse	IDP	-200	IIIA	
Drain power dissipation		P _D (Note 1)	100	mW	
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	–55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the



Weight: 0.75 mg (typ.)

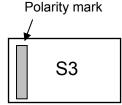
reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

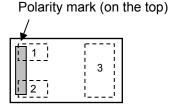
Note 1: Mounted on an FR4 board

 $(10 \text{ mm} \times 10 \text{ mm} \times 1.0 \text{ mm}, \text{Cu Pad: } 100 \text{ mm}^2)$

Marking (top view)

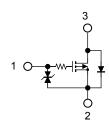


Pin Assignment (top view)



- 1. Gate
- 2. Source
- 3. Drain
- *Electrodes: on the bottom

Equivalent Circuit (top view)

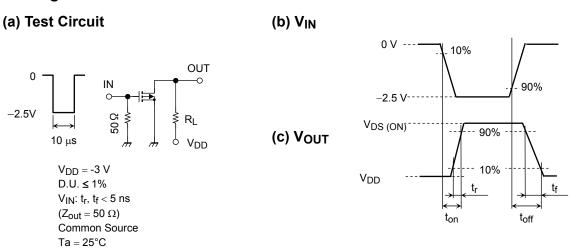


Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition		Min	Тур.	Max	Unit
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±10	μА
Drain-source brea	akdown voltage	V (BR) DSS	I _D = -0.1 mA, V _{GS} = 0 V		-20	_	_	V
Drain cutoff currer	nt	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		_	_	-1	μА
Gate threshold vol	tage	V _{th}	$V_{DS} = -3 \text{ V}, I_D = -1 \text{ mA}$		-0.4	_	-1.0	V
Forward transfer a	dmittance	Y _{fs}	$V_{DS} = -3 \text{ V}, I_D = -50 \text{ mA}$	(Note 2)	77	_	_	mS
Durin annua ON antistana		R _{DS} (ON)	$I_D = -50 \text{ mA}, V_{GS} = -4 \text{ V}$	(Note 2)	_	4.3	8	Ω
			$I_D = -50 \text{ mA}, V_{GS} = -2.5 \text{ V}$	(Note 2)	_	5.6	11	
Drain–source ON-resistance	I _D = -5 mA, V _{GS} = -1.5 V		(Note 2)		8.2	22		
			I _D = -2 mA, V _{GS} = -1.2 V	(Note 2)		11	44	
Input capacitance Reverse transfer capacitance		C _{iss}	$V_{DS} = -3 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$			12.2	_	pF
		C _{rss}				6.5	_	
Output capacitance		C _{oss}			_	10.4	_	
Switching time	Turn-on time	t _{on}	V _{DD} = -3 V, I _D = -50 mA, V _{GS} = 0 to -2.5 V		_	175	_	
	Turn-off time	t _{off}		_	251	_	ns	
Drain-source forward voltage		V _{DSF}	$I_D = 100 \text{ mA}, V_{GS} = 0 \text{ V}$	(Note 2)	_	0.83	1.2	V

Note 2: Pulse test

Switching Time Test Circuit



Usage Considerations

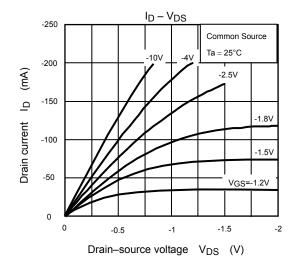
Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (–1 mA for the SSM3J35CT). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

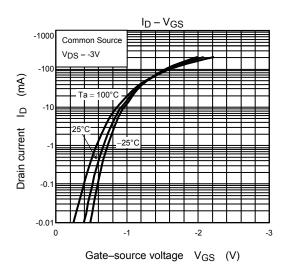
Take this into consideration when using the device.

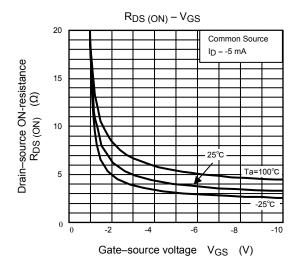
Handling Precaution

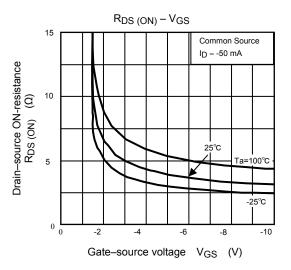
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

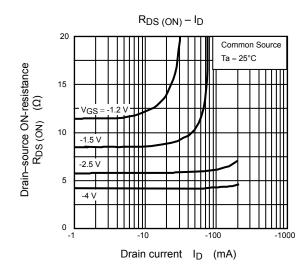
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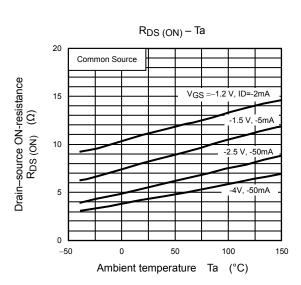


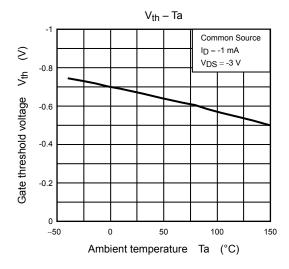


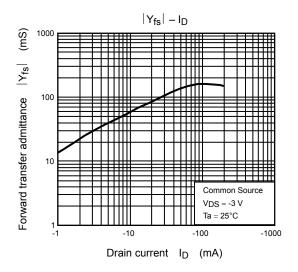


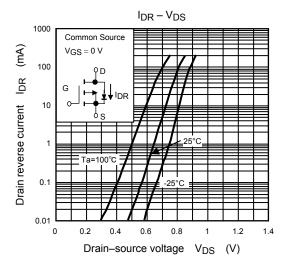


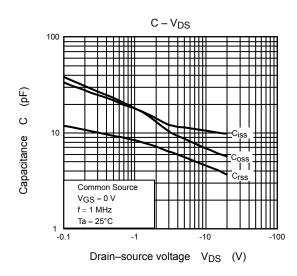


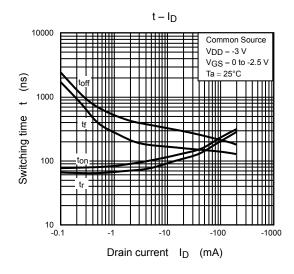


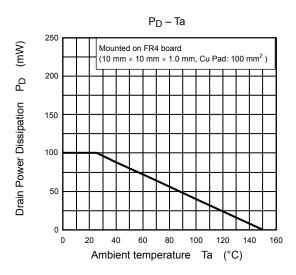












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